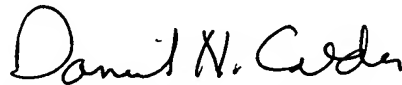


REMARKS

This is a divisional application of patent application Serial Number 08/815,656. The title and the specification have been amended. Claims 1-10 have been cancelled. Claims 11-19 remain and these claims are presented for examination.

Respectfully submitted,

RATNER & PRESTIA



Daniel N. Calder, Reg. No. 27,424  
Attorney for Applicants

DNC/pb

Attachment: Version with Markings to Show Changes Made

Dated: November 2, 2001

Suite 301

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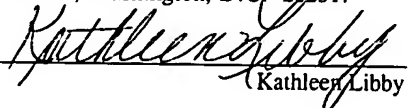
Valley Forge, PA 19482-0980

(610) 407-0700

The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 09-0457 (IBM Corporation) of any fees associated with this communication.

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Kathleen Libby

10001424-110201

VERSION WITH MARKINGS TO SHOW CHANGES MADEIN THE TITLE:

[PROCESS TO PRODUCE A HIGH TEMPERATURE  
INTERCONNECTION] LOW TEMPERATURE SOLDER CHIP ATTACH  
STRUCTURE.

IN THE SPECIFICATION:

Insert before the first line of the specification --This application  
is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on  
March 13, 1997, which has been allowed.--

IN THE CLAIMS:

Claims 1-10 have been cancelled.

10001421-110201